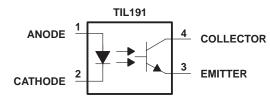
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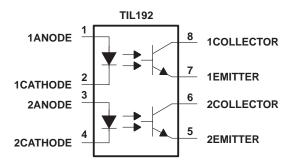
- Gallium-Arsenide-Diode Infrared Source
- Source Is Optically Coupled to Silicon npn Phototransistor
- Choice of One, Two, or Four Channels
- Choice of Three Current-Transfer Ratios
- High-Voltage Electrical Isolation 3.535 kV Peak (2.5 kV rms)
- Plastic Dual-In-Line Packages
- UL Listed File #E65085

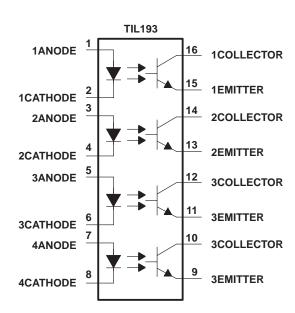
### description

These optocouplers consist of one gallium-arsenide light-emitting diode and one silicon npn phototransistor per channel. The TIL191 has a single channel in a 4-pin package, the TIL192 has two channels in an 8-package, and the TIL193 has four channels in a 16-pin package. The standard devices, TIL191, TIL192, and TIL193, are tested for a current-transfer ratio of 20% minimum. Devices selected for a current-transfer ratio of 50% and 100% minimum are designated with the suffix A and B respectively.

### schematic diagrams







## absolute maximum ratings at 25°C free-air (unless otherwise noted)†

Input-to-output voltage (see Note 1)	+3 535 kV poak or do (+3 5 kV rms)
Collector-emitter voltage (see Note 2)	
Emitter-collector voltage	
Input diode reverse voltage	5 V
Input diode continuous forward current at (or below) 25°C free-air to	emperature (see Note 3) 50 mA
Continuous total power dissipation at (or below) 25°C free-air temp	perature:
Phototransistor (see Note 4)	150 mW
Input diode plus phototransistor per channel (see Note 5)	200 mW
Storage temperature range, T <sub>stq</sub>	–55°C to 125°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds .	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. This rating applies for sine-wave operation at 50 Hz or 60 Hz. This capability is verified by testing in accordance with UL requirements.

- This value applies when the base-emitter diode is open circuited.
- 3. Derate linearly to 100°C free-air temperature at the rate of 0.67 mA/°C.
- 4. Derate linearly to 100°C free-air temperature at the rate of 2 mW/°C.
- 5. Derate linearly to 100°C free-air temperature at the rate of 2.67 mW/°C.



## TIL191, TIL192, TIL193, TIL191A, TIL192A, TIL193A TIL191B, TIL192B, TIL193B OPTOCOUPLERS

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## electrical characteristics 25°C free-air temperature range (unless otherwise noted)

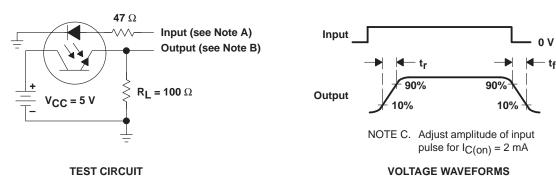
PARAMETER			TEST COND	MIN	TYP	MAX	UNIT	
V(BR)CEO	Collector-emitter breakdow	$I_C = 0.5 \text{ mA},$	IF = 0	35			V	
V(BR)ECO	Emitter-collector breakdow	I <sub>C</sub> = 100 μA,	IF = 0	7			V	
I <sub>R</sub>	Input diode static reverse of	V <sub>R</sub> = 5 V				10	μΑ	
IC(off))	Off-state collector current	V <sub>CE</sub> = 24 V,	IF = 0			100	nA	
	Current transfer ratio	TIL191, TIL192, TIL193		V <sub>CE</sub> = 5 V	20%			
CTR		TIL191A, TIL192A, TIL193A	I <sub>F</sub> = 5 mA,		50%			
		TIL191B, TIL192B, TIL193B			100%			
٧F	Input diode static forward v	I <sub>F</sub> = 20 mA				1.4	V	
VCE(sat)	Collector-emitter saturation	IF = 5 mA,	I <sub>C</sub> = 1 mA			0.4	V	
C <sub>io</sub>	Input-to-output capacitance		V <sub>in-out</sub> = 0 mA, See Note 6	f = 1 MHz,		1	·	pF
r <sub>io</sub>	Input-to-output internal res	$V_{in-out} = \pm 1 \text{ mA},$	See Note 6		10 <sup>11</sup>		Ω	

NOTE 6: These parameters are measured between all input diode leads shorted together and all phototransistor leads shorted together.

### switching characteristics at 25°C free-air temperature

	PARAMETER	TEST CO	MIN	TYP	MAX	UNIT	
t <sub>r</sub>	Rise time	V <sub>CC</sub> = 5 V,	$I_{C(on)} = 2 \text{ mA},$		6		
t <sub>f</sub>	Fall time	$R_L = 100 \Omega$ ,	See Figure 1		6		μs

### PARAMETER MEASUREMENT INFORMATION



NOTES: A. The input waveform is supplied by a generator with the following characteristics:  $Z_{OUT} = 50 \Omega$ ,  $t_{\Gamma} \le 15$  ns, duty cycle  $\approx 1\%$ ,  $t_{W} = 100 \text{ us}$ .

B. The output waveform is monitored on a oscilloscope with the following characteristic:  $t_{\Gamma} \le 12$  ns,  $R_{in} \ge 1$  M $\Omega$ ,  $C_{in} \le 20$  pF.

Figure 1. Switching Times



 $I_F = 2 \text{ mA}$ 

9 10

6 7

V<sub>CE</sub> - Collector-Emitter Voltage - V

**ON-STATE COLLECTOR CURRENT** 

(RELATIVE TO VALUE AT 25°C)

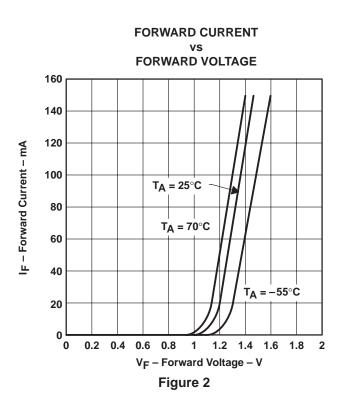
### **TYPICAL CHARACTERISTICS**

IC - Collector Current - mA

2

0

0 1 2 3



4 5

Figure 3

TIL191, TIL192, TIL193

ON-STATE COLLECTOR CURRENT (NORMALIZED)

VS

INDUIT DIODE FORWARD CURRENT

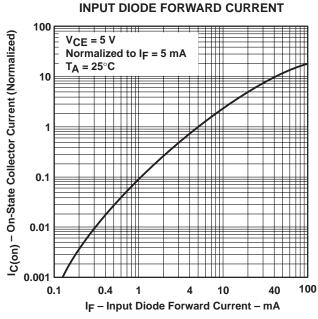


Figure 4

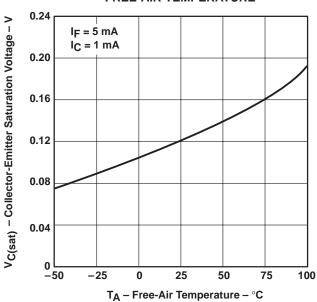
FREE-AIR TEMPERATURE 1.2 **VCE = 5 V**  $I_F = 5 \text{ mA}$ 1.1  $I_B = 0$ (Relative to Value at  $T_A = 25^{\circ}C$ ) 1 On-State Collector Current 0.9 0.8 0.7 0.6 0.5 0.4 -50 -25 25 50 75 100  $T_A$  – Free-Air Temperature –  $^{\circ}$ C

Figure 5

### TYPICAL CHARACTERISTICS

### **COLLECTOR-EMITTER SATURATION VOLTAGE**

# FREE-AIR TEMPERATURE



### Figure 6

### **APPLICATION INFORMATION**

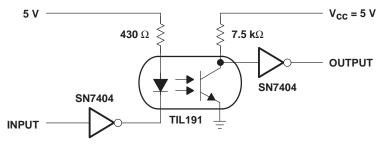
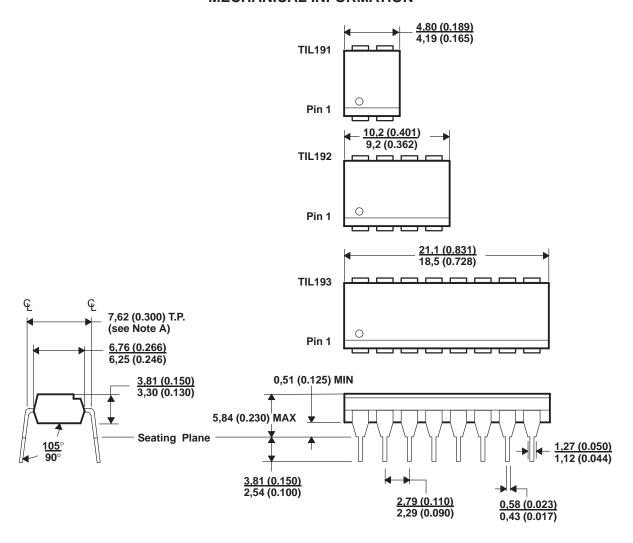


Figure 7

### **MECHANICAL INFORMATION**



NOTES: A. Each pin centerline is located within 0,25 (0.010) of its true longitudinal position.

B. All linear dimensions are given in millimeters and parenthetically given in inches.

Figure 8. Mechanical Information





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### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
TIL191	OBSOLETE	PDIP	N	4	TBD	Call TI	Call TI
TIL191A	OBSOLETE	PDIP	Р	4	TBD	Call TI	Call TI
TIL191B	OBSOLETE	PDIP	Р	4	TBD	Call TI	Call TI
TIL192	OBSOLETE	PDIP	N	8	TBD	Call TI	Call TI
TIL192A	OBSOLETE	PDIP	Р	8	TBD	Call TI	Call TI
TIL192B	OBSOLETE	PDIP	Р	8	TBD	Call TI	Call TI
TIL193	OBSOLETE	PDIP	N	16	TBD	Call TI	Call TI
TIL193A	OBSOLETE	PDIP	Р	16	TBD	Call TI	Call TI
TIL193B	OBSOLETE	PDIP	Р	16	TBD	Call TI	Call TI

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <a href="http://www.ti.com/productcontent">http://www.ti.com/productcontent</a> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

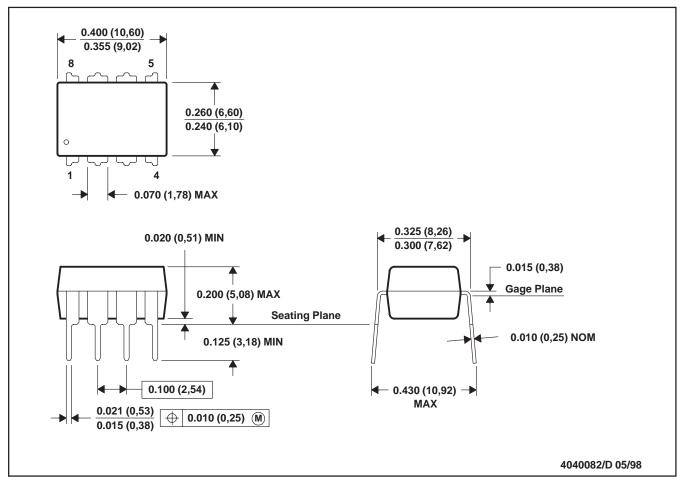
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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### P (R-PDIP-T8)

### PLASTIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

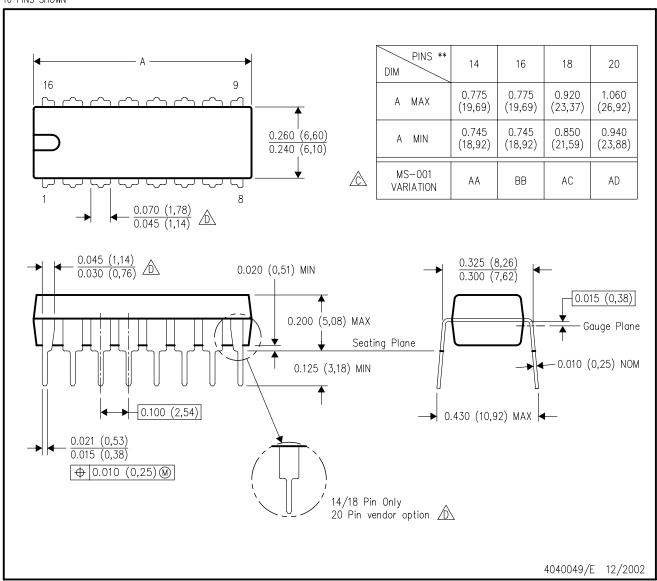
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001

For the latest package information, go to  $http://www.ti.com/sc/docs/package/pkg\_info.htm$ 

# N (R-PDIP-T\*\*)

# PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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